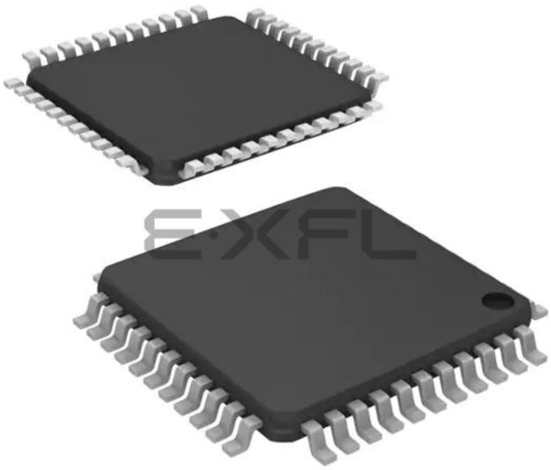

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	4KB (2K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f4221t-i-pt

TABLE 3-2: CAPACITOR SELECTION FOR QUARTZ CRYSTALS

Osc Type	Crystal Freq	Typical Capacitor Values Tested: C1	C2
LP	32 kHz	22 pF	22 pF
XT	1 MHz 4 MHz	22 pF 22 pF	22 pF 22 pF
HS	4 MHz 10 MHz 20 MHz 25 MHz	22 pF 22 pF 22 pF 22 pF	22 pF 22 pF 22 pF 22 pF

Capacitor values are for design guidance only.

Different capacitor values may be required to produce acceptable oscillator operation. The user should test the performance of the oscillator over the expected VDD and temperature range for the application. Refer to the following application notes for oscillator specific information:

- *AN588, "PIC® Microcontroller Oscillator Design Guide"*
- *AN826, "Crystal Oscillator Basics and Crystal Selection for rfPIC® and PIC® Devices"*
- *AN849, "Basic PIC® Oscillator Design"*
- *AN943, "Practical PIC® Oscillator Analysis and Design"*
- AN949, "Making Your Oscillator Work"

See the notes following this table for additional information.

Note 1: Higher capacitance increases the stability of the oscillator but also increases the start-up time.

2: When operating below 3V VDD, or when using certain ceramic resonators at any voltage, it may be necessary to use the HS mode or switch to a crystal oscillator.

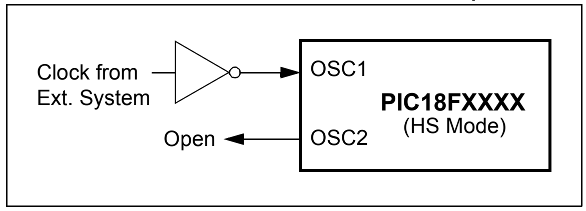
3: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

4: Rs may be required to avoid overdriving crystals with low drive level specification.

5: Always verify oscillator performance over the VDD and temperature range that is expected for the application.

An external clock source may also be connected to the OSC1 pin in the HS mode, as shown in Figure 3-2. When operated in this mode, parameters D033 and D043 apply.

FIGURE 3-2: EXTERNAL CLOCK INPUT OPERATION (HS OSC CONFIGURATION)

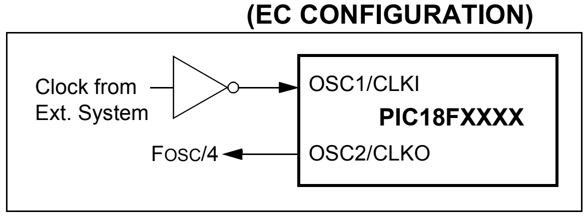


3.3 External Clock Input

The EC and ECIO Oscillator modes require an external clock source to be connected to the OSC1 pin. There is no oscillator start-up time required after a Power-on Reset or after an exit from Sleep mode.

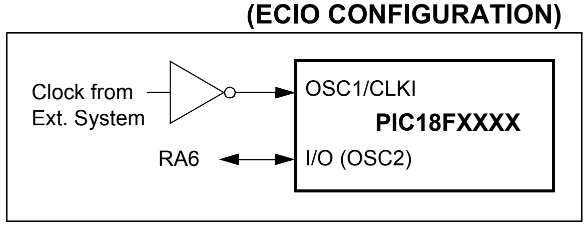
In the EC Oscillator mode, the oscillator frequency divided by 4 is available on the OSC2 pin. This signal may be used for test purposes or to synchronize other logic. Figure 3-3 shows the pin connections for the EC Oscillator mode.

FIGURE 3-3: EXTERNAL CLOCK INPUT OPERATION (EC CONFIGURATION)



The ECIO Oscillator mode functions like the EC mode, except that the OSC2 pin becomes an additional general purpose I/O pin. The I/O pin becomes bit 6 of PORTA (RA6). Figure 3-4 shows the pin connections for the ECIO Oscillator mode. When operated in this mode, parameters D033A and D043A apply.

FIGURE 3-4: EXTERNAL CLOCK INPUT OPERATION (ECIO CONFIGURATION)



5.5 Device Reset Timers

PIC18F2221/2321/4221/4321 family devices incorporate three separate on-chip timers that help regulate the Power-on Reset process. Their main function is to ensure that the device clock is stable before code is executed. These timers are:

- Power-up Timer (PWRT)
- Oscillator Start-up Timer (OST)
- PLL Lock Time-out

5.5.1 POWER-UP TIMER (PWRT)

The Power-up Timer (PWRT) of the PIC18F2221/2321/4221/4321 family devices is an 11-bit counter which uses the INTRC source as the clock input. This yields an approximate time interval of 2048 x 32 μs = 65.6 ms. While the PWRT is counting, the device is held in Reset.

The power-up time delay depends on the INTRC clock and will vary from chip to chip due to temperature and process variation. See DC parameter 33 for details.

The PWRT is enabled by clearing the $\overline{\text{PWRTEN}}$ Configuration bit.

5.5.2 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over (parameter 33). This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP, HS and HSPLL modes and only on Power-on Reset, or on exit from most power-managed modes.

5.5.3 PLL LOCK TIME-OUT

With the PLL enabled in HSPLL mode, the time-out sequence following a Power-on Reset is slightly different from other oscillator modes. A separate timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (TPLL) is typically 2 ms and follows the oscillator start-up time-out.

5.5.4 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows:

1. After the POR pulse has cleared, PWRT time-out is invoked (if enabled).
2. Then, the OST is activated.

The total time-out will vary based on oscillator configuration and the status of the PWRT. Figure 5-3, Figure 5-4, Figure 5-5, Figure 5-6 and Figure 5-7 all depict time-out sequences on power-up, with the Power-up Timer enabled and the device operating in HS Oscillator mode. Figures 5-3 through 5-6 also apply to devices operating in XT or LP modes. For devices in RC mode and with the PWRT disabled, there will be no time-out at all.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, all time-outs will expire. Bringing $\overline{\text{MCLR}}$ high will begin execution immediately (Figure 5-5). This is useful for testing purposes or to synchronize more than one PIC18FXXXX device operating in parallel.

TABLE 5-2: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up(2) and Brown-out Reset		Exit from Power-Managed Mode
	$\overline{\text{PWRTEN}}$ = 0	$\overline{\text{PWRTEN}}$ = 1	
HSPLL	66 ms(1) + 1024 TOSC + 2 ms(2)	1024 TOSC + 2 ms(2)	1024 TOSC + 2 ms(2)
HS, XT, LP	66 ms(1) + 1024 TOSC	1024 TOSC	1024 TOSC
EC, ECIO	66 ms(1)	—	—
RC, RCIO	66 ms(1)	—	—
INTIO1, INTIO2	66 ms(1)	—	—

Note 1: 66 ms (65.5 ms) is the nominal Power-up Timer (PWRT) delay.

2: 2 ms is the nominal time required for the PLL to lock.

6.1.2.2 Return Stack Pointer (STKPTR)

The STKPTR register (Register 6-1) contains the Stack Pointer value, the STKFUL (Stack Full) status bit and the STKUNF (Stack Underflow) status bits. The value of the Stack Pointer can be 0 through 31. The Stack Pointer increments before values are pushed onto the stack and decrements after values are popped off the stack. On Reset, the Stack Pointer value will be zero. The user may read and write the Stack Pointer value. This feature can be used by a Real-Time Operating System (RTOS) for return stack maintenance.

After the PC is pushed onto the stack 31 times (without popping any values off the stack), the STKFUL bit is set. The STKFUL bit is cleared by software or by a POR.

The action that takes place when the stack becomes full depends on the state of the STVREN (Stack Overflow Reset Enable) Configuration bit. (Refer to **Section 24.1 "Configuration Bits"** for a description of the device Configuration bits.) If STVREN is set (default), the 31st push will push the (PC + 2) value onto the stack, set the STKFUL bit and reset the device. The STKFUL bit will remain set and the Stack Pointer will be set to zero.

If STVREN is cleared, the STKFUL bit will be set on the 31st push and the Stack Pointer will increment to 31. Any additional pushes will not overwrite the 31st push and STKPTR will remain at 31.

When the stack has been popped enough times to unload the stack, the next pop will return a value of zero to the PC and sets the STKUNF bit, while the Stack Pointer remains at zero. The STKUNF bit will remain set until cleared by software or until a POR occurs.

Note:	Returning a value of zero to the PC on an underflow has the effect of vectoring the program to the Reset vector, where the stack conditions can be verified and appropriate actions can be taken. This is not the same as a Reset, as the contents of the SFRs are not affected.

6.1.2.3 `PUSH` and `POP` Instructions

Since the Top-of-Stack is readable and writable, the ability to push values onto the stack and pull values off the stack without disturbing normal program execution is a desirable feature. The PIC18 instruction set includes two instructions, `PUSH` and `POP`, that permit the TOS to be manipulated under software control. TOSU, TOSH and TOSL can be modified to place data or a return address on the stack.

The `PUSH` instruction places the current PC value onto the stack. This increments the Stack Pointer and loads the current PC value onto the stack.

The `POP` instruction discards the current TOS by decrementing the Stack Pointer. The previous value pushed onto the stack then becomes the TOS value.

REGISTER 6-1: STKPTR: STACK POINTER REGISTER

R/C-0	R/C-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STKFUL(1)	STKUNF(1)	—	SP4	SP3	SP2	SP1	SP0
bit 7							bit 0

bit 7 **STKFUL:** Stack Full Flag bit(1)
`1` = Stack became full or overflowed
`0` = Stack has not become full or overflowed

bit 6 **STKUNF:** Stack Underflow Flag bit(1)
`1` = Stack underflow occurred
`0` = Stack underflow did not occur

bit 5 **Unimplemented:** Read as '`0`'

bit 4-0 **SP<4:0>:** Stack Pointer Location bits

Note 1: Bit 7 and bit 6 are cleared by user software or by a POR.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	C = Clearable only bit
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

6.2.3 INSTRUCTIONS IN PROGRAM MEMORY

The program memory is addressed in bytes. Instructions are stored as two bytes or four bytes in program memory. The Least Significant Byte of an instruction word is always stored in a program memory location with an even address (LSb = `0`). To maintain alignment with instruction boundaries, the PC increments in steps of 2 and the LSb will always read '`0`' (see **Section 6.1.1 "Program Counter"**).

Figure 6-4 shows an example of how instruction words are stored in the program memory.

The `CALL` and `GOTO` instructions have the absolute program memory address embedded into the instruction. Since instructions are always stored on word boundaries, the data contained in the instruction is a word address. The word address is written to PC<20:1>, which accesses the desired byte address in program memory. Instruction #2 in Figure 6-4 shows how the instruction `GOTO 0006h` is encoded in the program memory. Program branch instructions, which encode a relative address offset, operate in the same manner. The offset value stored in a branch instruction represents the number of single-word instructions that the PC will be offset by. **Section 24.0 "Instruction Set Summary"** provides further details of the instruction set.

FIGURE 6-4: INSTRUCTIONS IN PROGRAM MEMORY

Program Memory Byte Locations →

		LSB = 1	LSB = 0	Word Address ↓
				000000h
				000002h
				000004h
				000006h
Instruction 1:	`MOVLW 055h`	0Fh	55h	000008h
Instruction 2:	`GOTO 0006h`	EFh	03h	00000Ah
		F0h	00h	00000Ch
Instruction 3:	`MOVFF 123h, 456h`	C1h	23h	00000Eh
		F4h	56h	000010h
				000012h
				000014h

6.2.4 TWO-WORD INSTRUCTIONS

The standard PIC18 instruction set has four two-word instructions: `CALL`, `MOVFF`, `GOTO` and `LSFR`. In all cases, the second word of the instructions always has '`1111`' as its four Most Significant bits; the other 12 bits are literal data, usually a data memory address.

The use of '`1111`' in the 4 MSbs of an instruction specifies a special form of `NOP`. If the instruction is executed in proper sequence – immediately after the first word – the data in the second word is accessed and used by the instruction sequence. If the first word is skipped for some reason and the second word is executed by itself, a `NOP` is executed instead. This is necessary for cases when the two-word instruction is preceded by a conditional instruction that changes the PC. Example 6-4 shows how this works.

Note:	See **Section 6.6 "PIC18 Instruction Execution and the Extended Instruction Set"** for information on two-word instructions in the extended instruction set.

EXAMPLE 6-4: TWO-WORD INSTRUCTIONS

CASE 1:

Object Code	Source Code
`0110 0110 0000 0000`	`TSTFSZ REG1 ; is RAM location 0?`
`1100 0001 0010 0011`	`MOVFF REG1, REG2 ; No, skip this word`
`1111 0100 0101 0110`	`; Execute this word as a NOP`
`0010 0100 0000 0000`	`ADDWF REG3 ; continue code`

CASE 2:

Object Code	Source Code
`0110 0110 0000 0000`	`TSTFSZ REG1 ; is RAM location 0?`
`1100 0001 0010 0011`	`MOVFF REG1, REG2 ; Yes, execute this word`
`1111 0100 0101 0110`	`; 2nd word of instruction`
`0010 0100 0000 0000`	`ADDWF REG3 ; continue code`

EXAMPLE 7-3: WRITING TO FLASH PROGRAM MEMORY (CONTINUED)

```
PROGRAM_MEMORY
               BCF     INTCON, GIE           ; disable interrupts
               MOVLW   55h                   ; required sequence
               MOVWF   EECON2                ; write 55h
               MOVLW   0AAh
               MOVWF   EECON2                ; write AAh
               BSF     EECON1, WR            ; start program (CPU stall)
               NOP
               BSF     INTCON, GIE           ; re-enable interrupts
               DECFSZ  COUNTER_HI            ; loop until done
               GOTO    PROGRAM_LOOP
               BCF     EECON1, WREN          ; disable write to memory
```

7.5.2 WRITE VERIFY

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

7.5.3 UNEXPECTED TERMINATION OF WRITE OPERATION

If a write is terminated by an unplanned event, such as loss of power or an unexpected Reset, the memory location just programmed should be verified and reprogrammed if needed. If the write operation is interrupted by a $\overline{\text{MCLR}}$ Reset or a WDT Time-out Reset during normal operation, the user can check the WRERR bit and rewrite the location(s) as needed.

7.5.4 PROTECTION AGAINST SPURIOUS WRITES

To protect against spurious writes to Flash program memory, the write initiate sequence must also be followed. See **Section 24.0 “Special Features of the CPU”** for more detail.

7.6 Flash Program Operation During Code Protection

See **Section 24.5 “Program Verification and Code Protection”** for details on code protection of Flash program memory.

TABLE 7-2: REGISTERS ASSOCIATED WITH PROGRAM FLASH MEMORY

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
TBLPTRU	—	—	bit 21	Program Memory Table Pointer Upper Byte (TBLPTR<20:16>)					55
TBPLTRH	Program Memory Table Pointer High Byte (TBLPTR<15:8>)								55
TBLPTRL	Program Memory Table Pointer Low Byte (TBLPTR<7:0>)								55
TABLAT	Program Memory Table Latch								55
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	55
EECON2	EEPROM Control Register 2 (not a physical register)								57
EECON1	EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD	57
IPR2	OSCFIP	CMIP	—	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	58
PIR2	OSCFIF	CMIF	—	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	58
PIE2	OSCFIE	CMIE	—	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	58

Legend: — = unimplemented, read as ‘0’. Shaded cells are not used during Flash/EEPROM access.

8.5 Operation During Code-Protect

Data EEPROM memory has its own code-protect bits in Configuration Words. External read and write operations are disabled if code protection is enabled.

The microcontroller itself can both read and write to the internal data EEPROM, regardless of the state of the code-protect Configuration bit. Refer to **Section 24.0 "Special Features of the CPU"** for additional information.

8.6 Protection Against Spurious Write

To protect against spurious EEPROM writes, various mechanisms have been implemented. On power-up, the WREN bit is cleared. In addition, writes to the EEPROM are blocked during the Power-up Timer period (T_{PWRT}, parameter 33).

The write initiate sequence and the WREN bit together help prevent an accidental write during Brown-out Reset, power glitch or software malfunction.

8.7 Using the Data EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing data. Such data is typically updated at least one time within the number of writes defined by specification, D124. If any location storing data is not written at least this often, the data EEPROM array must be refreshed. For this reason, values that change infrequently, or not at all, should be stored in Flash program memory.

A simple data EEPROM refresh routine is shown in Example 8-3.

Note:	If data EEPROM is only used to store constants and/or data that changes often, an array refresh is likely not required. See specification, D124.

EXAMPLE 8-3: DATA EEPROM REFRESH ROUTINE

```
        CLRF    EEADR           ; Start at address 0
        BCF     EECON1, CFGS    ; Set for memory
        BCF     EECON1, EEPGD   ; Set for Data EEPROM
        BCF     INTCON, GIE     ; Disable interrupts
        BSF     EECON1, WREN    ; Enable writes
LOOP                            ; Loop to refresh array
        BSF     EECON1, RD      ; Read current address
        MOVLW   55h             ;
        MOVWF   EECON2          ; Write 55h
        MOVLW   0AAh            ;
        MOVWF   EECON2          ; Write 0AAh
        BSF     EECON1, WR      ; Set WR bit to begin write
        BTFSC   EECON1, WR      ; Wait for write to complete
        BRA     $-2
        INCFSZ  EEADR, F        ; Increment address
        BRA     LOOP            ; Not zero, do it again

        BCF     EECON1, WREN    ; Disable writes
        BSF     INTCON, GIE     ; Enable interrupts
```

9.0 8 x 8 HARDWARE MULTIPLIER

9.1 Introduction

All PIC18 devices include an 8 x 8 hardware multiplier as part of the ALU. The multiplier performs an unsigned operation and yields a 16-bit result that is stored in the product register pair, PRODH:PRODL. The multiplier's operation does not affect any flags in the STATUS register.

Making multiplication a hardware operation allows it to be completed in a single instruction cycle. This has the advantages of higher computational throughput and reduced code size for multiplication algorithms and allows the PIC18 devices to be used in many applications previously reserved for digital signal processors. A comparison of various hardware and software multiply operations, along with the savings in memory and execution time, is shown in Table 9-1.

9.2 Operation

Example 9-1 shows the instruction sequence for an 8 x 8 unsigned multiplication. Only one instruction is required when one of the arguments is already loaded in the WREG register.

Example 9-2 shows the sequence to do an 8 x 8 signed multiplication. To account for the sign bits of the arguments, each argument's Most Significant bit (MSb) is tested and the appropriate subtractions are done.

EXAMPLE 9-1: 8 x 8 UNSIGNED MULTIPLY ROUTINE

```
MOVF    ARG1, W     ;
MULWF   ARG2        ; ARG1 * ARG2 ->
                    ; PRODH:PRODL
```

EXAMPLE 9-2: 8 x 8 SIGNED MULTIPLY ROUTINE

```
MOVF    ARG1, W
MULWF   ARG2        ; ARG1 * ARG2 ->
                    ; PRODH:PRODL
BTFSC   ARG2, SB    ; Test Sign Bit
SUBWF   PRODH, F    ; PRODH = PRODH
                    ;         - ARG1
MOVF    ARG2, W
BTFSC   ARG1, SB    ; Test Sign Bit
SUBWF   PRODH, F    ; PRODH = PRODH
                    ;         - ARG2
```

TABLE 9-1: PERFORMANCE COMPARISON FOR VARIOUS MULTIPLY OPERATIONS

Routine	Multiply Method	Program Memory (Words)	Cycles (Max)	Time		
				@ 40 MHz	@ 10 MHz	@ 4 MHz
8 x 8 unsigned	Without hardware multiply	13	69	6.9 μs	27.6 μs	69 μs
	Hardware multiply	1	1	100 ns	400 ns	1 μs
8 x 8 signed	Without hardware multiply	33	91	9.1 μs	36.4 μs	91 μs
	Hardware multiply	6	6	600 ns	2.4 μs	6 μs
16 x 16 unsigned	Without hardware multiply	21	242	24.2 μs	96.8 μs	242 μs
	Hardware multiply	28	28	2.8 μs	11.2 μs	28 μs
16 x 16 signed	Without hardware multiply	52	254	25.4 μs	102.6 μs	254 μs
	Hardware multiply	35	40	4.0 μs	16.0 μs	40 μs

TABLE 11-3: PORTB I/O SUMMARY

Pin	Function	TRIS Setting	I/O	I/O Type	Description
RB0/INT0/FLT0/ AN12	RB0	0	O	DIG	LATB<0> data output; not affected by analog input.
		1	I	TTL	PORTB<0> data input; weak pull-up when $\overline{RBPU}$ bit is cleared. Disabled when analog input enabled.(1)
	INT0	1	I	ST	External Interrupt 0 input.
	FLT0	1	I	ST	Enhanced PWM Fault input (ECCP1 module); enabled in software.
	AN12	1	I	ANA	A/D Input Channel 12.(1)
RB1/INT1/AN10	RB1	0	O	DIG	LATB<1> data output; not affected by analog input.
		1	I	TTL	PORTB<1> data input; weak pull-up when $\overline{RBPU}$ bit is cleared. Disabled when analog input enabled.(1)
	INT1	1	I	ST	External Interrupt 1 input.
	AN10	1	I	ANA	A/D Input Channel 10.(1)
RB2/INT2/AN8	RB2	0	O	DIG	LATB<2> data output; not affected by analog input.
		1	I	TTL	PORTB<2> data input; weak pull-up when $\overline{RBPU}$ bit is cleared. Disabled when analog input enabled.(1)
	INT2	1	I	ST	External Interrupt 2 input.
	AN8	1	I	ANA	A/D Input Channel 8.(1)
RB3/AN9/CCP2	RB3	0	O	DIG	LATB<3> data output; not affected by analog input.
		1	I	TTL	PORTB<3> data input; weak pull-up when $\overline{RBPU}$ bit is cleared. Disabled when analog input enabled.(1)
	AN9	1	I	ANA	A/D Input Channel 9.(1)
	CCP2(2)	0	O	DIG	CCP2 compare and PWM output.
		1	I	ST	CCP2 capture input.
RB4/KBI0/AN11	RB4	0	O	DIG	LATB<4> data output; not affected by analog input.
		1	I	TTL	PORTB<4> data input; weak pull-up when $\overline{RBPU}$ bit is cleared. Disabled when analog input enabled.(1)
	KBI0	1	I	TTL	Interrupt-on-change pin.
	AN11	1	I	ANA	A/D Input Channel 11.(1)
RB5/KBI1/PGM	RB5	0	O	DIG	LATB<5> data output.
		1	I	TTL	PORTB<5> data input; weak pull-up when $\overline{RBPU}$ bit is cleared.
	KBI1	1	I	TTL	Interrupt-on-change pin.
	PGM	x	I	ST	Single-Supply Programming mode entry (ICSP™). Enabled by LVP Configuration bit; all other pin functions disabled.
RB6/KBI2/PGC	RB6	0	O	DIG	LATB<6> data output.
		1	I	TTL	PORTB<6> data input; weak pull-up when $\overline{RBPU}$ bit is cleared.
	KBI2	1	I	TTL	Interrupt-on-change pin.
	PGC	x	I	ST	Serial execution (ICSP™) clock input for ICSP and ICD operation.(3)
RB7/KBI3/PGD	RB7	0	O	DIG	LATB<7> data output.
		1	I	TTL	PORTB<7> data input; weak pull-up when $\overline{RBPU}$ bit is cleared.
	KBI3	1	I	TTL	Interrupt-on-change pin.
	PGD	x	O	DIG	Serial execution data output for ICSP and ICD operation.(3)
		x	I	ST	Serial execution data input for ICSP and ICD operation.(3)

Legend: DIG = Digital level output; TTL = TTL input buffer; ST = Schmitt Trigger input buffer; ANA = Analog level input/output; x = Don't care (TRIS bit does not affect port direction or is overridden for this option).

Note 1: Configuration on POR is determined by the PBADEN Configuration bit. Pins are configured as analog inputs by default when PBADEN is set and digital inputs when PBADEN is cleared.

2: Alternate assignment for CCP2 when the CCP2MX Configuration bit is '0'. Default assignment is RC1.

3: All other pin functions are disabled when ICSP or ICD are enabled.

13.0 TIMER1 MODULE

The Timer1 timer/counter module incorporates these features:

- Software selectable operation as a 16-bit timer or counter
- Readable and writable 8-bit registers (TMR1H and TMR1L)
- Selectable clock source (internal or external) with device clock or Timer1 oscillator internal options
- Interrupt-on-overflow
- Reset on CCP Special Event Trigger
- Device clock status flag (T1RUN)

A simplified block diagram of the Timer1 module is shown in Figure 13-1. A block diagram of the module's operation in Read/Write mode is shown in Figure 13-2.

The module incorporates its own low-power oscillator to provide an additional clocking option. The Timer1 oscillator can also be used as a low-power clock source for the microcontroller in power-managed operation.

Timer1 can also be used to provide Real-Time Clock (RTC) functionality to applications with only a minimal addition of external components and code overhead.

Timer1 is controlled through the T1CON Control register (Register 13-1). It also contains the Timer1 Oscillator Enable bit (T1OSCEN). Timer1 can be enabled or disabled by setting or clearing control bit, TMR1ON (T1CON<0>).

REGISTER 13-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RD16	T1RUN	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	TMR1CS	TMR1ON
bit 7							bit 0

bit 7 **RD16:** 16-Bit Read/Write Mode Enable bit
1 = Enables register read/write of TImer1 in one 16-bit operation
0 = Enables register read/write of Timer1 in two 8-bit operations

bit 6 **T1RUN:** Timer1 System Clock Status bit
1 = Device clock is derived from Timer1 oscillator
0 = Device clock is derived from another source

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
11 = 1:8 Prescale value
10 = 1:4 Prescale value
01 = 1:2 Prescale value
00 = 1:1 Prescale value

bit 3 **T1OSCEN:** Timer1 Oscillator Enable bit
1 = Timer1 oscillator is enabled
0 = Timer1 oscillator is shut off
The oscillator inverter and feedback resistor are turned off to eliminate power drain.

bit 2 **$\overline{\text{T1SYNC}}$:** Timer1 External Clock Input Synchronization Select bit
When TMR1CS = 1:
1 = Do not synchronize external clock input
0 = Synchronize external clock input
When TMR1CS = 0:
This bit is ignored. Timer1 uses the internal clock when TMR1CS = 0.

bit 1 **TMR1CS:** Timer1 Clock Source Select bit
1 = External clock from pin RC0/T1OSO/T13CKI (on the rising edge)
0 = Internal clock (FOSC/4)

bit 0 **TMR1ON:** Timer1 On bit
1 = Enables Timer1
0 = Stops Timer1

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

18.3.1 REGISTERS

The MSSP module has four registers for SPI mode operation. These are:

- MSSP Control Register 1 (SSPCON1)
- MSSP Status Register (SSPSTAT)
- Serial Receive/Transmit Buffer Register (SSPBUF)
- MSSP Shift Register (SSPSR) – Not directly accessible

SSPCON1 and SSPSTAT are the control and status registers in SPI mode operation. The SSPCON1 register is readable and writable. The lower 6 bits of the SSPSTAT are read-only. The upper two bits of the SSPSTAT are read/write.

SSPSR is the shift register used for shifting data in or out. SSPBUF is the buffer register to which data bytes are written to or read from.

In receive operations, SSPSR and SSPBUF together create a double-buffered receiver. When SSPSR receives a complete byte, it is transferred to SSPBUF and the SSPIF interrupt is set.

During transmission, the SSPBUF is not double-buffered. A write to SSPBUF will write to both SSPBUF and SSPSR.

REGISTER 18-1: SSPSTAT: MSSP STATUS REGISTER (SPI MODE)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	$D/\overline{A}$	P	S	$R/\overline{W}$	UA	BF
bit 7							bit 0

bit 7 **SMP:** Sample bit
SPI Master mode:
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
SPI Slave mode:
SMP must be cleared when SPI is used in Slave mode.

bit 6 **CKE:** SPI Clock Select bit
1 = Transmit occurs on transition from active to Idle clock state
0 = Transmit occurs on transition from Idle to active clock state

Note: Polarity of clock state is set by the CKP bit (SSPCON1<4>).

bit 5 **$D/\overline{A}$:** Data/$\overline{\text{Address}}$ bit
Used in I^2C™ mode only.

bit 4 **P:** Stop bit
Used in I^2C mode only. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.

bit 3 **S:** Start bit
Used in I^2C mode only.

bit 2 **$R/\overline{W}$:** Read/$\overline{\text{Write}}$ Information bit
Used in I^2C mode only.

bit 1 **UA:** Update Address bit
Used in I^2C mode only.

bit 0 **BF:** Buffer Full Status bit (Receive mode only)
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

18.3.3 ENABLING SPI I/O

To enable the serial port, MSSP Enable bit, SSPEN (SSPCON1<5>), must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, reinitialize the SSPCON registers and then set the SSPEN bit. This configures the SDI, SDO, SCK and $\overline{SS}$ pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed as follows:

- SDI is automatically controlled by the SPI module
- SDO must have TRISC<5> bit cleared
- SCK (Master mode) must have TRISC<3> bit cleared
- SCK (Slave mode) must have TRISC<3> bit set
- $\overline{SS}$ must have TRISA<5> bit set

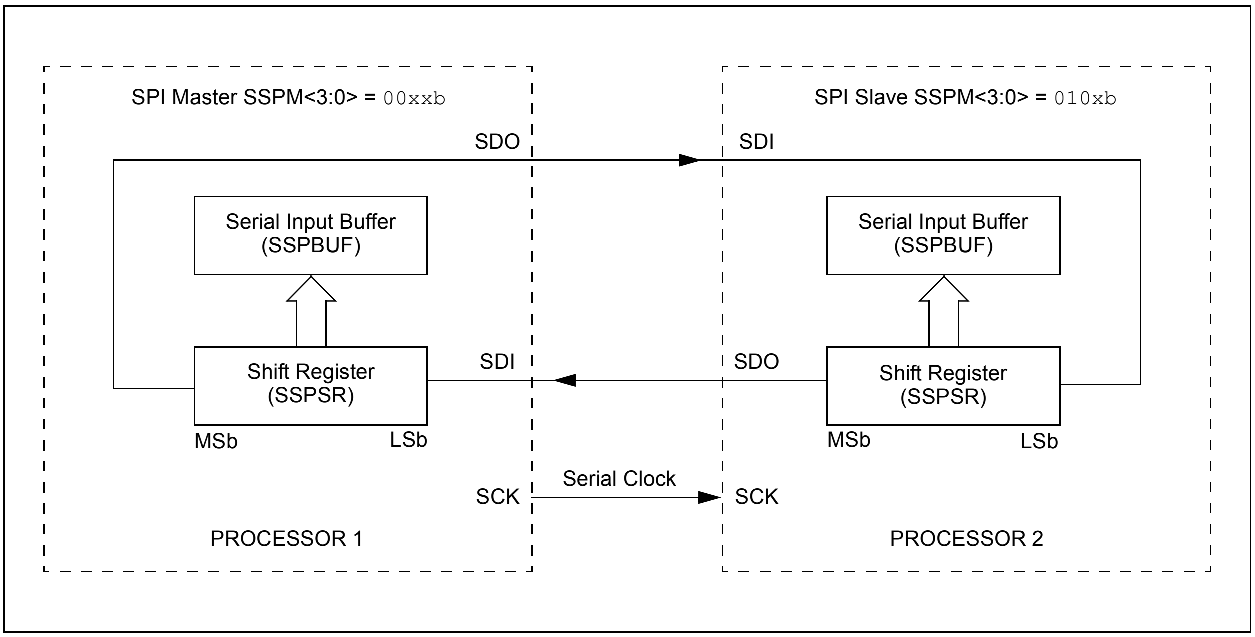
Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value.

18.3.4 TYPICAL CONNECTION

Figure 18-2 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge and latched on the opposite edge of the clock. Both processors should be programmed to the same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- Master sends data – Slave sends dummy data
- Master sends data – Slave sends data
- Master sends dummy data – Slave sends data

FIGURE 18-2: SPI MASTER/SLAVE CONNECTION



EXAMPLE 19-1: CALCULATING BAUD RATE ERROR

For a device with FOSC of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

Desired Baud Rate = FOSC/(64 ([SPBRGH:SPBRG] + 1))

Solving for SPBRGH:SPBRG:

X = ((FOSC/Desired Baud Rate)/64) – 1
= ((16000000/9600)/64) – 1
= [25.042] = 25

Calculated Baud Rate = 16000000/(64 (25 + 1))
= 9615

Error = (Calculated Baud Rate – Desired Baud Rate)/Desired Baud Rate
= (9615 – 9600)/9600 = 0.16%

TABLE 19-2: REGISTERS ASSOCIATED WITH BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	57
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	57
BAUDCON	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	—	WUE	ABDEN	57
SPBRGH	EUSART Baud Rate Generator Register High Byte								57
SPBRG	EUSART Baud Rate Generator Register Low Byte								57

Legend: — = unimplemented, read as '0'. Shaded cells are not used by the BRG.

REGISTER 24-8: CONFIG6L: CONFIGURATION REGISTER 6 LOW (BYTE ADDRESS 30000Ah)

U-0	U-0	U-0	U-0	U-0	U-0	R/C-1	R/C-1
—	—	—	—	—	—	WRT1	WRT0
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **WRT1:** Write Protection bit
1 = Block 1 not write-protected(1)
0 = Block 1 write-protected(1)

bit 0 **WRT0:** Write Protection bit
1 = Block 0 not write-protected(1)
0 = Block 0 write-protected(1)

Note 1: See Figure 24-5 for variable block boundaries.

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

REGISTER 24-9: CONFIG6H: CONFIGURATION REGISTER 6 HIGH (BYTE ADDRESS 30000Bh)

R/C-1	R/C-1	R-1	U-0	U-0	U-0	U-0	U-0
WRTD	WRTB	WRTC(1)	—	—	—	—	—
bit 7							bit 0

bit 7 **WRTD:** Data EEPROM Write Protection bit
1 = Data EEPROM not write-protected
0 = Data EEPROM write-protected

bit 6 **WRTB:** Boot Block Write Protection bit
1 = Boot block not write-protected(2)
0 = Boot block write-protected(2)

bit 5 **WRTC:** Configuration Register Write Protection bit(1)
1 = Configuration registers (300000-3000FFh) not write-protected
0 = Configuration registers (300000-3000FFh) write-protected

bit 4-0 **Unimplemented:** Read as '0'

Note 1: This bit is read-only in normal execution mode; it can be written only in Program mode.
2: See Figure 24-5 for block boundaries.

Legend:		
R = Readable bit	C = Clearable bit	U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed		u = Unchanged from programmed state

24.5.2 DATA EEPROM CODE PROTECTION

The entire data EEPROM is protected from external reads and writes by two bits: CPD and WRTD. CPD inhibits external reads and writes of data EEPROM. WRTD inhibits internal and external writes to data EEPROM. The CPU can always read data EEPROM under normal operation, regardless of the protection bit settings.

24.5.3 CONFIGURATION REGISTER PROTECTION

The Configuration registers can be write-protected. The WRTC bit controls protection of the Configuration registers. In normal execution mode, the WRTC bit is readable only. WRTC can only be written via ICSP operation or an external programmer.

24.6 ID Locations

Eight memory locations (200000h-200007h) are designated as ID locations, where the user can store checksum or other code identification numbers. These locations are both readable and writable during normal execution through the `TBLRD` and `TBLWT` instructions or during program/verify. The ID locations can be read when the device is code-protected.

24.7 In-Circuit Serial Programming

PIC18F2221/2321/4221/4321 family microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

24.8 In-Circuit Debugger

When the $\overline{\text{DEBUG}}$ Configuration bit is programmed to a '0', the In-Circuit Debugger functionality is enabled. This function allows simple debugging functions when used with MPLAB® IDE. When the microcontroller has this feature enabled, some resources are not available for general use. Table 24-4 shows which resources are required by the background debugger.

TABLE 24-4: DEBUGGER RESOURCES

I/O Pins:	RB6, RB7
Stack:	2 levels
Program Memory:	512 bytes
Data Memory:	10 bytes

To use the In-Circuit Debugger function of the microcontroller, the design must implement In-Circuit Serial Programming connections to $\overline{\text{MCLR}}$/VPP/RE3, VDD, VSS, RB7 and RB6. This will interface to the In-Circuit Debugger module available from Microchip or one of the third party development tool companies.

24.9 Single-Supply ICSP Programming

The LVP Configuration bit enables Single-Supply ICSP Programming (formerly known as *Low-Voltage ICSP Programming* or *LVP*). When Single-Supply Programming is enabled, the microcontroller can be programmed without requiring high voltage being applied to the $\overline{\text{MCLR}}$/VPP/RE3 pin, but the RB5/KBI1/PGM pin is then dedicated to controlling Program mode entry and is not available as a general purpose I/O pin.

While programming, using Single-Supply Programming, VDD is applied to the $\overline{\text{MCLR}}$/VPP/RE3 pin as in normal execution mode. To enter Programming mode, VDD is applied to the PGM pin.

> **Note 1:** High-voltage programming is always available, regardless of the state of the LVP bit or the PGM pin, by applying VIHH to the $\overline{\text{MCLR}}$ pin.
>
> **2:** By default, Single-Supply ICSP Programming is enabled in unprogrammed devices (as supplied from Microchip) and erased devices.
>
> **3:** When Single-Supply ICSP Programming is enabled, the RB5 pin can no longer be used as a general purpose I/O pin.
>
> **4:** When LVP is enabled, externally pull the PGM pin to VSS to allow normal program execution.

If Single-Supply ICSP Programming mode will not be used, the LVP bit can be cleared. RB5/KBI1/PGM then becomes available as the digital I/O pin, RB5. The LVP bit may be set or cleared only when using standard high-voltage programming (VIHH applied to the $\overline{\text{MCLR}}$/VPP/RE3 pin). Once LVP has been disabled, only the standard high-voltage programming is available and must be used to program the device.

Memory that is not code-protected can be erased using either a block erase, or erased row by row, then written at any specified VDD. If code-protected memory is to be erased, a block erase is required. If a block erase is to be performed when using Low-Voltage ICSP Programming, the device must be supplied with VDD of 4.5V to 5.5V.

TABLE 25-2: PIC18FXXXX INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	16-Bit Instruction Word				Status Affected	Notes
				MSb			LSb		
BYTE-ORIENTED OPERATIONS									
ADDWF	f, d, a	Add WREG and f	1	0010	01da0	ffff	ffff	C, DC, Z, OV, N	1, 2
ADDWFC	f, d, a	Add WREG and Carry bit to f	1	0010	0da	ffff	ffff	C, DC, Z, OV, N	1, 2
ANDWF	f, d, a	AND WREG with f	1	0001	01da	ffff	ffff	Z, N	1,2
CLRF	f, a	Clear f	1	0110	101a	ffff	ffff	Z	2
COMF	f, d, a	Complement f	1	0001	11da	ffff	ffff	Z, N	1, 2
CPFSEQ	f, a	Compare f with WREG, Skip =	1 (2 or 3)	0110	001a	ffff	ffff	None	4
CPFSGT	f, a	Compare f with WREG, Skip >	1 (2 or 3)	0110	010a	ffff	ffff	None	4
CPFSLT	f, a	Compare f with WREG, Skip <	1 (2 or 3)	0110	000a	ffff	ffff	None	1, 2
DECF	f, d, a	Decrement f	1	0000	01da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
DECFSZ	f, d, a	Decrement f, Skip if 0	1 (2 or 3)	0010	11da	ffff	ffff	None	1, 2, 3, 4
DCFSNZ	f, d, a	Decrement f, Skip if Not 0	1 (2 or 3)	0100	11da	ffff	ffff	None	1, 2
INCF	f, d, a	Increment f	1	0010	10da	ffff	ffff	C, DC, Z, OV, N	1, 2, 3, 4
INCFSZ	f, d, a	Increment f, Skip if 0	1 (2 or 3)	0011	11da	ffff	ffff	None	4
INFSNZ	f, d, a	Increment f, Skip if Not 0	1 (2 or 3)	0100	10da	ffff	ffff	None	1, 2
IORWF	f, d, a	Inclusive OR WREG with f	1	0001	00da	ffff	ffff	Z, N	1, 2
MOVF	f, d, a	Move f	1	0101	00da	ffff	ffff	Z, N	1
MOVFF	f_s, f_d	Move f_s (source) to 1st Word	2	1100	ffff	ffff	ffff	None	
		f_d (destination) 2nd Word		1111	ffff	ffff	ffff		
MOVWF	f, a	Move WREG to f	1	0110	111a	ffff	ffff	None	
MULWF	f, a	Multiply WREG with f	1	0000	001a	ffff	ffff	None	1, 2
NEGF	f, a	Negate f	1	0110	110a	ffff	ffff	C, DC, Z, OV, N	
RLCF	f, d, a	Rotate Left f through Carry	1	0011	01da	ffff	ffff	C, Z, N	1, 2
RLNCF	f, d, a	Rotate Left f (No Carry)	1	0100	01da	ffff	ffff	Z, N	
RRCF	f, d, a	Rotate Right f through Carry	1	0011	00da	ffff	ffff	C, Z, N	
RRNCF	f, d, a	Rotate Right f (No Carry)	1	0100	00da	ffff	ffff	Z, N	
SETF	f, a	Set f	1	0110	100a	ffff	ffff	None	1, 2
SUBFWB	f, d, a	Subtract f from WREG with Borrow	1	0101	01da	ffff	ffff	C, DC, Z, OV, N	
SUBWF	f, d, a	Subtract WREG from f	1	0101	11da	ffff	ffff	C, DC, Z, OV, N	1, 2
SUBWFB	f, d, a	Subtract WREG from f with Borrow	1	0101	10da	ffff	ffff	C, DC, Z, OV, N	
SWAPF	f, d, a	Swap Nibbles in f	1	0011	10da	ffff	ffff	None	4
TSTFSZ	f, a	Test f, Skip if 0	1 (2 or 3)	0110	011a	ffff	ffff	None	1, 2
XORWF	f, d, a	Exclusive OR WREG with f	1	0001	10da	ffff	ffff	Z, N	

Note 1: When a PORT register is modified as a function of itself (e.g., `MOVF PORTB, 1, 0`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

2: If this instruction is executed on the TMR0 register (and where applicable, 'd' = 1), the prescaler will be cleared if assigned.

3: If the Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a `NOP`.

4: Some instructions are two-word instructions. The second word of these instructions will be executed as a `NOP` unless the first word of the instruction retrieves the information embedded in these 16 bits. This ensures that all program memory locations have a valid instruction.

26.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

26.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

27.2 DC Characteristics: Power-Down and Supply Current PIC18F2221/2321/4221/4321 (Industrial) PIC18LF2221/2321/4221/4321 (Industrial)

PIC18LF2221/2321/4221/4321 (Industrial)		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial				
PIC18F2221/2321/4221/4321 (Industrial, Extended)		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device**	**Typ**	**Max**	**Units**	**Conditions**	
	Power-Down Current (IPD)(1)					
	PIC18LF2X21/4X21	0.5	0.7	μA	-40°C	VDD = 2.0V (**Sleep** mode)
		0.5	0.7	μA	+25°C	
		0.5	1.7	μA	+85°C	
	PIC18LF2X21/4X21	0.6	0.9	μA	-40°C	VDD = 3.0V (**Sleep** mode)
		0.6	0.9	μA	+25°C	
		0.6	1.9	μA	+85°C	
	All Devices	0.9	2.0	μA	-40°C	VDD = 5.0V (**Sleep** mode)
		0.9	2.0	μA	+25°C	
		0.9	6.5	μA	+85°C	
	Extended Devices Only	7.5	70	μA	+125°C	

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS, and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;
MCLR = VDD; WDT enabled/disabled as specified.

3: Low-power, Timer1 oscillator is selected unless otherwise indicated, where LPT1OSC (CONFIG3H<2>) = 1.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

5: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0.

27.4 AC (Timing) Characteristics

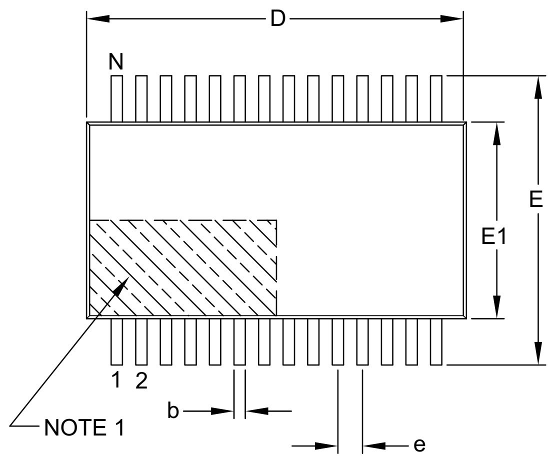
27.4.1 TIMING PARAMETER SYMBOLOGY

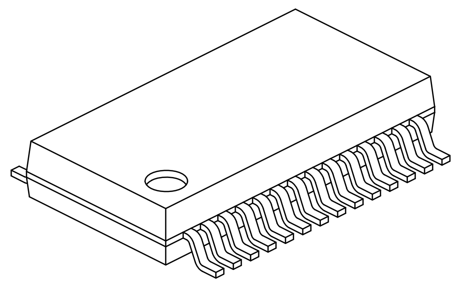
The timing parameter symbols have been created using one of the following formats:

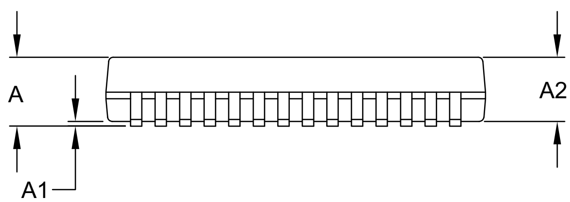
1. TppS2ppS		3. TCC:ST	(I^2C specifications only)
2. TppS		4. Ts	(I^2C specifications only)
T			
F	Frequency	T	Time
Lowercase letters (pp) and their meanings:			
pp			
cc	CCP1	osc	OSC1
ck	CLKO	rd	$\overline{RD}$
cs	$\overline{CS}$	rw	$\overline{RD}$ or $\overline{WR}$
di	SDI	sc	SCK
do	SDO	ss	$\overline{SS}$
dt	Data in	t0	T0CKI
io	I/O port	t1	T13CKI
mc	$\overline{MCLR}$	wr	$\overline{WR}$
Uppercase letters and their meanings:			
S			
F	Fall	P	Period
H	High	R	Rise
I	Invalid (High-impedance)	V	Valid
L	Low	Z	High-impedance
I^2C only			
AA	output access	High	High
BUF	Bus free	Low	Low
TCC:ST (I^2C specifications only)			
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	Stop condition
STA	Start condition		

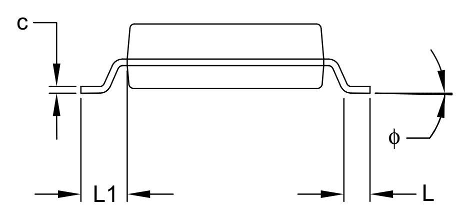
28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging









	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

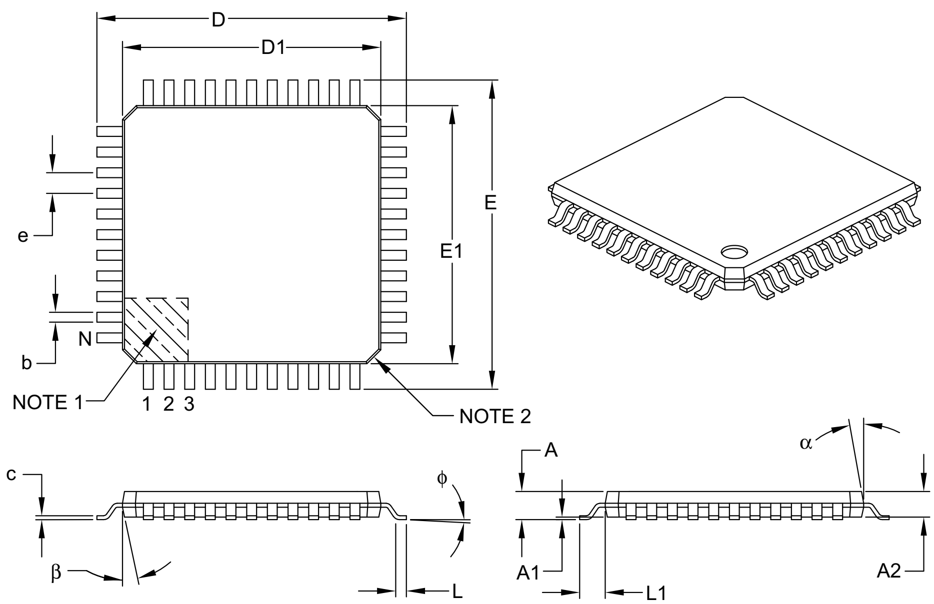
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	44		
Lead Pitch	e	0.80 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.30	0.37	0.45
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B